

News Release

For Immediate Release

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ITW EAE Wins SbS Excellence Gold Award for MPM® Edison II ACT (Automatic Changeover Technology)

Lakeville, Minnesota, November 7, 2024 – ITW EAE is proud to announce that it has earned a 2024 SbS Excellence Gold Award for MPM's Edison II ACT. The MPM® Edison™ II ACT is a state-of-the-art automated changeover solution for establishing a solid step ahead toward the industry mega trend. It is designed for simplicity, ease of adoption, scalability, and creating attractive ROI for users.



The Step-by-Step Excellence Awards (SbSEA) program is the most influential program for the EMS industry in China. Winners are judged by technical experts in the field, senior executives from the downstream industry, and dedicated Step-by-Step New Technologies Magazine's (SbSTM) readers. The SbS Excellence Gold Award is given to the entry that have contributed significant impact on the advancement of electronics assembly

technologies or processes for the industry. The award was presented at Nepcon Asia 2024 in Shenzhen, China.

The MPM® Edison™ II ACT is the industry's most accurate printer in the market with advanced technology needed for ultra-fine pitch and micro aperture printing processes. This makes it ideally suited for advanced semiconductor stencil printing applications. The MPM® Edison™ II ACT has a proven print process capability greater than 2 Cpk for 0201 metric components. With a built-in ± 8 micron machine alignment, and ± 15 micron wet print accuracy (≥ 2 Cpk @ 6 sigma, Edison's wet print accuracy is 25% better than the next best printers.

MPM® Edison™ II ACT has a transfer efficiency that exceeds requirements for the smallest apertures. A single high precision load-cell with closed-loop pressure control and motor driven system enable precise and consistent squeegee force control across the entire print stroke in both directions, which helps improve yields. Innovative machine design achieves ultra-tight coplanarity between stencil and substrate enabling yield improvement for ultra-thin stencil printing.

"We thank and appreciate the recognition of this innovation by the industry experts", said Wayne Wang, ITW EAE Printer Business Manager. "Edison II ACT provides an cost-effective solution for labor intensive and error prone product changeover task, it enables quicker & simpler, reduced labor dependence, and error free changeover".

ITW EAE, a division of Illinois Tool Works, Inc., is the global leader in process knowledge, services and manufacture of capital equipment used in the printed circuit board assembly and semiconductor industries. The group brings together the world's leading brands of electronics assembly equipment: MPM Printers, Camalot Dispensers, Electrovert Cleaners and Soldering Solutions, Vitronics Soltec Soldering Solutions and Despatch Thermal Processing Technology. For more information visit www.itweae.com.